

Newly Added Section

Related Applications

This application claims priority under 35 U.S.C. §119 from Malaysian patent application serial number PI 20004237, filed September 13, 2000.

Amended Claims

3.(amended) A stress-free lead frame (1) as claimed in Claim 1 further characterised by said plurality of stress-relief means (15) [(12)] being holes and slots.

4.(amended) A stress-free lead frame (1) [(2)] as claimed in Claim 3 [1] further characterised by said holes and slots being arranged in multiple rows.

5.(amended) A stress-free lead frame (1) [(2)] as claimed in Claim 2 further characterised by said interlocking means (16) being a plurality of slots.

6.(amended) A stress-free lead frame (1) as claimed in Claim 4 [or Claim 5] further characterised in that [by] said holes and slots are arranged side by side at equal intervals.

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